As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR CONDUCTING HEAT IN A FLIP-CHIP ASSEMBLY, the specification of which (check one):

is attached hereto.				
✓ was filed on June 20, 2001 as Un✓ was filed on as PCT	ited States application serial no. 09/885,615.			
as PC1	international application no and wa	as amended under PCT Article 19 on		
I hereby state that I have reviewed and referred to above.	understand the contents of the above-identified s	pecification, including the claims, as ame	ended by any a	mendment
I acknowledge the duty to displace to a	ho II G. Data			
matter claimed in this application, as "mat	he U.S. Patent and Trademark Office all informateriality" is defined in Title 37, Code of Federal R	ion known to me to be material to the pa legulations § 1.56.	tentability of th	e subject
I hereby claim foreign priority benefits	under Title 35, United States Code, § 119(a)-(d) ional application(s) designating at least one count	07.8.365(4) 05		
attached continuation name and have also is	South of L.	y outer than the United States of Americ	a listed balow a	and an area
on which priority is claimed.	neithred below and on any attached continuation nating at least one country other than the United S	tates of America having a filing date before	ore that of the	application(s)
Prior foreign/PCT application(s):				
en de En de		Priority Claimed		
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	(day/month/year filed)		
I hereby claim the benefit under Title 35	, United States Code, § 120 of any United States ted below and on any attached continuation page application in the manner provided by the first r	•	Yes	No
Regulations § 1.56 which became available I	r application in the manner provided by the first general Office all information known to me to be returned to the filing date of such prior application a	naterial to patentability as defined in Titl and the national or PCT international filin	e 37, Code of I g date of this a	Federal pplication:
	(filing date)	(status - pending, patented or	abandoned)	
(application serial no.)	(filing date)	(status - pending, patented or a	(bandoned)	
I hereby claim the benefit under Title 35, (provisional application no.)	United States Code, § 119(e) of any United State (filing date)	es provisional application(s) listed below:		
I hereby appoint the following Registered I	Practicionam to assess at the second			~
therewith:	Practitioners to prosecute this application and to t	ransact all business in the Patent and Tra	demark Office	connected
David V. Trask, Reg. No. 22,012 Joseph A. Walkowski, Reg. No. 28,765 Edgar R. Cataxinos, Reg. No. 39,931 Kenneth B. Ludwig, Reg. No. 42,814 Krista Weber-Powell, Reg. No. P-47,867 Bradley B. Jensen, Reg. No. 46,801 Michael L. Lynch, Reg. No. 30,871	William S. Britt, Reg. No. 20,969 James R. Duzan, Reg. No. 28,393 Kent S. Burningham, Reg. No. 30,453 Paul C. Oestreich, Reg. No. 44,983 Devin R. Jensen, Reg. No. 44,805 Jarett K. Abramson, Reg. No. P-47,376 Cheele R. Parent	Laurence B. Bond, Reg. No. 30,54 Allen C. Turner, Reg. No. 33,041 Brick G. Power, Reg. No. 38,581 David L. Stott, Reg. No. 43,937 Samuel E. Webb, Reg. No. 44,394 Katherine A. Hamer, Reg. No. P-4		
	Charles B. Brantley II, Reg. No. 38,086	, 3	.,-20	
P.O.	s R. Duzan, telephone no. (801) 532-1922. SK BRITT BOX 2550			
I hereby declare that all statements made has	Lake City, Utah 84110			
and further that these statements were made wit both, under Section 1001 of Title 18 of the Unit issued thereon.	rein of my own knowledge are true and that all si h the knowledge that willful false statements and ted States Code and that such willful false statem	tatements made on information and belie the like so made are punishable by fine ents may jeopardize the validity of the a	f are believed to or imprisonme oplication or an	o be true; nt, or y patent
Full name of first joint inventor: Salman Akran Inventor's signature Residence: Boise, Idaho	- /\	16th August 2001		
Citizenship: Pakistan Post Office Address: 1463 E. Regatta Street, Bo		0 '		



DECLARATION FOR PATENT APPLICA (continuation page)

Invention title: METHOD AND APPARATUS FOR CONDUCTING HEAT IN A FLIP-CHIP ASSEMBLY

Inventor name(s) appearing on first declaration page: Salman Akram

Additional original, first and joint inventor(s):

Full name of second joint inventor: Min G. Wood Inventor's signature
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 1366 E. Versailles Ct., Boise, ID 83706

_ Date (Chay . 16 , 2001